

4

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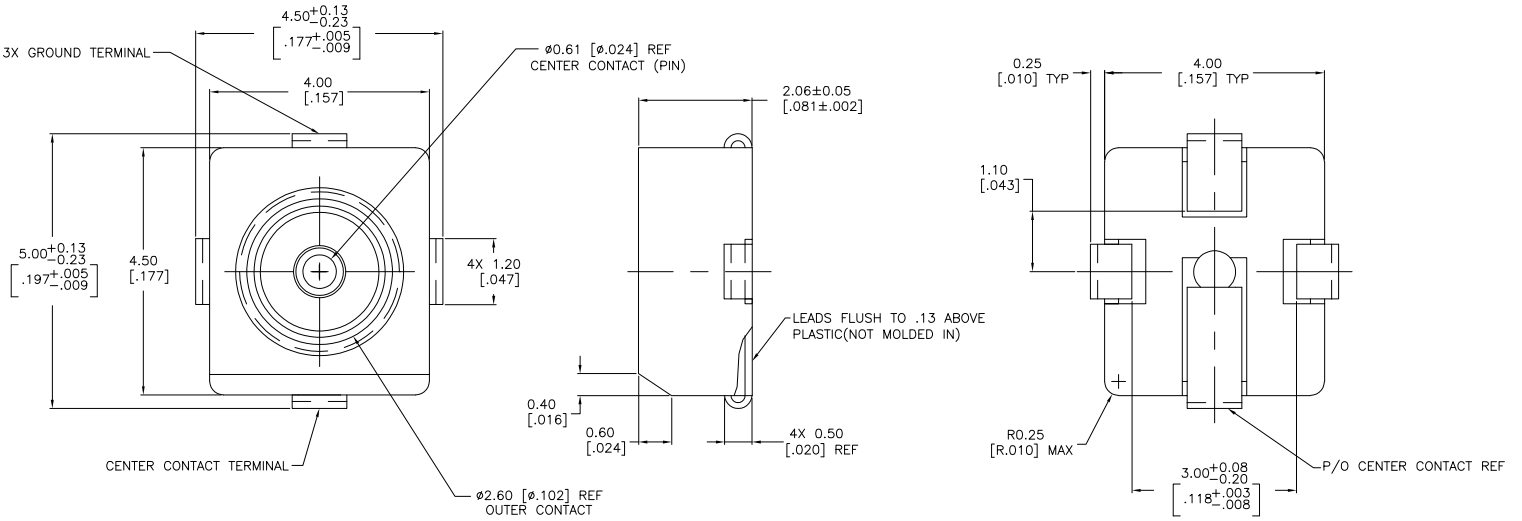
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1

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LOC		DIBT		REVISIONS			
F	LTR	DESCRIPTION	DATE	BY	APP'D		
AJ	17	C	REDRAWN PER EC OS14-0016-05	18JAN05	BM	KW	

- 1 MATERIAL:
HOUSING: POLYPHENYLENE SULFIDE.
CONTACTS: COPPER ALLOY CDA 752.
- 2 FINISH:
CONTACTS: GOLD PLATE OVER DUCTILE NICKEL PLATE.



1055687-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DRN P. RESNICK 12/20/91	Tyco Electronics Corporation Harrisburg, Pa 17105-3608
DIMENSIONS: mm [INCHES]		CHK -	
DIMENSIONS UNLESS OTHERWISE SPECIFIED: 0 PLG ± .010 1 PLG ± .010 2 PLG ± 0.13(.005) 3 PLG ± .010 4 PLG ± .010 ANGLES ± 1°		APD P. RESNICK 05/13/92	NAME
MATERIAL		APPLICATION SPEC	SIZE CASE CODE DRAWING NO
FINISH		WEIGHT	A2 00779 C=1055687
		CUSTOMER DRAWING	RESTRICTED TO
			SCALE 20:1 SHEET 1 OF 2 REV C

AMP 1471-9 REV 31MM2000

1055687

A

4

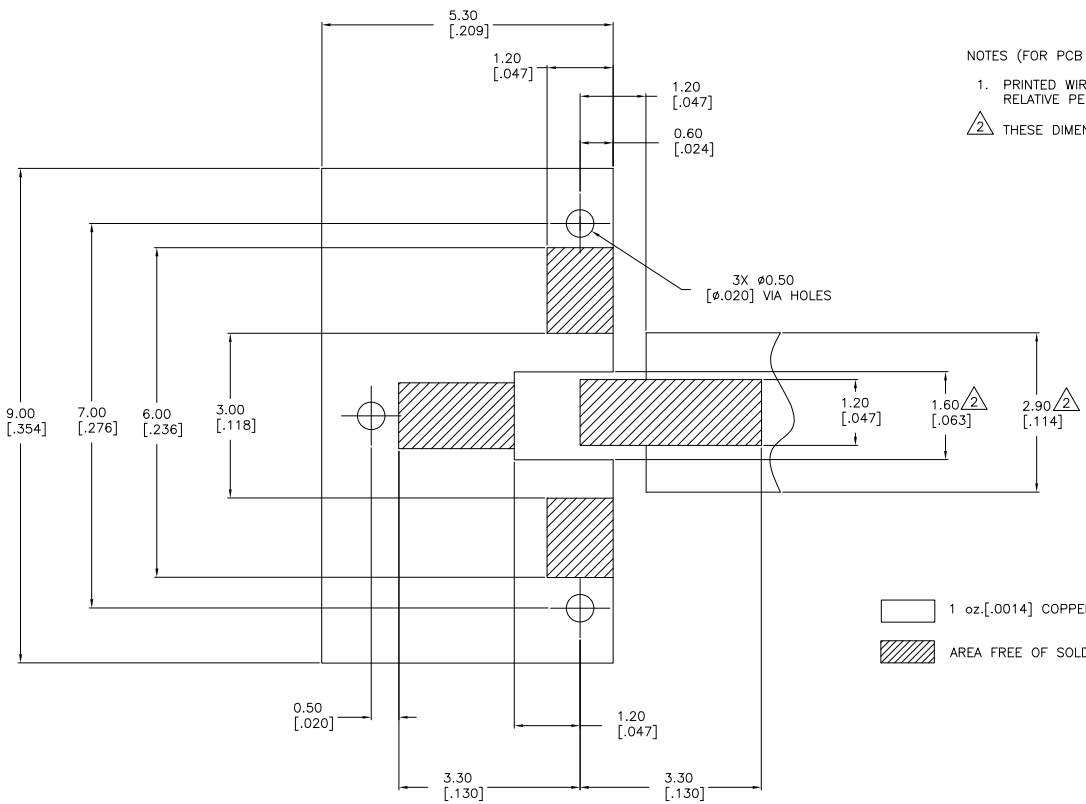
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2

1

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LOC	DIST	REVISIONS					
		F	LR	DESCRIPTION	DATE	DRN	APD
AJ	17	-	-	SEE SHEET 1	-	-	-



NOTES (FOR PCB LAYOUT ONLY):
 1. PRINTED WIRING BOARD MATERIAL: GLASS EPOXY, FR-4 OR SIMILAR, RELATIVE PERMITTIVITY: 4.8oz. COPPER CLAD BOTH SIDES.
 2. THESE DIMENSIONS VALID FOR 1.60[.062] BOARD THICKNESS.

RECOMMENDED MOUNTING PATTERN FOR MICROSTRIP LINE

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DIMENSIONS:		CHK	P. RESNICK	-	Harrisburg, Pa 17105-3608		
mm [MCHES]		DATE	05/13/92	NAME	STRAIGHT OSMT PCB		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APD	P. RESNICK	-	MOUNT PLUG RECEPTACLE		
0 PLG	±	PRODUCT SPEC	-	APPLICATION SPEC	SIZE	CAGE CODE	DRAWING NO.
1 PLG	±	-	-	WEIGHT	A2	00779	C=1055687
2 PLG	±	-	-	CUSTOMER DRAWING	SCALE	20:1	SHEET 2 OF 2
3 PLG	±	-	-	RESTRICTED TO			
4 PLG	±	-	-	REV C			
ANGLES	±	-	-				

AMP 1471-9 REV 31MM2000

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